

CMPA5585025F

25 W, 5.5 - 8.5 GHz, GaN MMIC, Power Amplifier

Cree's CMPA5585025F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC). GaN has superior properties compared to silicon or gallium arsenide, including higher breakdown voltage, higher saturated electron drift velocity and higher thermal conductivity. GaN HEMTs also offer greater power density and wider bandwidths compared to Si and GaAs transistors. This MMIC is available in

CREE CMP M5585025F CMP M5585025F

> PN: CMPA5585025F Package Type: 440208

a 10 lead metal/ceramic flanged package for optimal electrical and thermal performance.

Typical Performance Over 5.8-8.4 GHz $(T_c = 25^{\circ}c)$

Parameter	5.8 GHz	6.4 GHz	7.2 GHz	7.9 GHz	8.4 GHz	Units
Small Signal Gain	29.5	24.0	24.0	24.0	22.0	dB
Output Power ¹	15	23	20	19	19	W
Power Gain ¹	22.5	20.0	18.5	17.5	20.0	dB
Power Added Efficiency ¹	30	35	30	25	30	%

Note¹: Measured at -30 dBc, 1.6 MHz from carrier, in the CMPA5585025F-TB under OQPSK modulation, 1.6 Msps, PN23, Alpha Filter = 0.2.

Features

- 25 dB Small Signal Gain
- 35 W Typical P_{SAT}
- Operation up to 28 V
- High Breakdown Voltage
- High Temperature Operation
- Size 1.00 x 0.385 inches

Applications

- Point to Point Radio
- Communications
- Satellite Communication Uplink



Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	V _{DSS}	84	V _{DC}	25°C
Gate-source Voltage	$V_{\sf GS}$	-10, +2	V _{DC}	25°C
Power Dissipation	P _{DISS}	55	W	
Storage Temperature	T _{STG}	-65, +150	°C	
Operating Junction Temperature	T ₃	225	°C	
Maximum Forward Gate Current	\mathbf{I}_{GMAX}	10	mA	25°C
Soldering Temperature ¹	T_s	245	°C	
Screw Torque	τ	40	in-oz	
Thermal Resistance, Junction to Case	$R_{_{\theta JC}}$	1.55	°C/W	OQPSK, 85° C, $P_{DISS} = 55 \text{ W}$
Thermal Resistance, Junction to Case	$R_{_{ heta JC}}$	1.80	°C/W	CW, 85° C, $P_{DISS} = 77 \text{ W}$
Case Operating Temperature	T _c	-40, +140	°C	$P_{DISS} = 55 \text{ W}$
Case Operating Temperature	T _c	-40, +85	°C	$P_{DISS} = 77 \text{ W}$

Note:

Electrical Characteristics (Frequency = 5.5 GHz to 8.5 GHz unless otherwise stated; $T_c = 25$ °C)

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
DC Characteristics¹						
Gate Threshold Voltage	$V_{GS(TH)}$	-3.8	-3.0	-2.3	V	$V_{DS} = 10 \text{ V, } I_{D} = 13.2 \text{ mA}$
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	V_{DC}	$V_{DS} = 28 \text{ V, } I_{D} = 285 \text{ A}$
Saturated Drain Current ²	$I_{\scriptscriptstyle DS}$	10.6	12.8	-	Α	$V_{DS} = 6.0 \text{ V, } V_{GS} = 2.0 \text{ V}$
Drain-Source Breakdown Voltage	$V_{\scriptscriptstyle BD}$	84	100	-	V	$V_{GS} = -8 \text{ V, } I_{D} = 13.2 \text{ mA}$
RF Characteristics ³						
Small Signal Gain	S21	18.25	24	-	dB	$V_{DD} = 28 \text{ V, I}_{DQ} = 285 \text{ mA,}$ $P_{IN} = -20 \text{ dBm}$
Input Return Loss	S11	-	10	-	dB	$V_{DD} = 28 \text{ V, } I_{DQ} = 285 \text{ mA}$
Output Return Loss	S22	-	6	-	dB	$V_{_{DD}} = 28 \text{ V, } I_{_{DQ}} = 285 \text{ mA}$
Output Mismatch Stress	VSWR	-	-	5:1	Ψ	No damage at all phase angles, $V_{DD} = 28$ V, $I_{DQ} = 285$ mA, $P_{OUT} = 25$ W OQPSK

Notes:

¹ Refer to the Application Note on soldering at www.cree.com/products/wireless_appnotes.asp

¹ Measured on-wafer prior to packaging.

² Scaled from PCM data.

³ Measured in the CMPA5585025F-TB.



Electrical Characteristics Continued... $(T_c = 25^{\circ}C)$

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
RF Characteristics ^{1,2,3,4}						
Power Added Efficiency	PAE1	20.0	24.5	-	%	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 5.8 GHz
Power Added Efficiency	PAE2	17.0	21.0	-	%	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 7.2 GHz
Power Added Efficiency	PAE3	16.0	19.0	-	%	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 7.9 GHz
Power Added Efficiency	PAE4	17.5	21.5	-	%	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 8.4 GHz
Power Gain	G_{p_1}	19.5	23.0	-	dB	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 5.8 GHz
Power Gain	G_{p_2}	16.5	19.0	-	dB	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 7.2 GHz
Power Gain	G _{P3}	17.3	19.5	-	dB	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 7.9 GHz
Power Gain	$G_{p_{4}}$	18.5	21.5	-	dB	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 8.4 GHz
OQPSK Linearity	ACLR1	-	-34.5	-28.5	dB	$V_{DD} = 28 \text{ V}, I_{DQ} = 285 \text{ mA},$ Frequency = 5.8 GHz
OQPSK Linearity	ACLR2	-	-37.5	-30.0	dB	$V_{_{\mathrm{DD}}} = 28 \text{ V}, \ \mathrm{I}_{_{\mathrm{DQ}}} = 285 \text{ mA},$ Frequency = 7.2 GHz
OQPSK Linearity	ACLR3	-	-31.0	-26.0	dB	$V_{\scriptscriptstyle DD}$ = 28 V, $I_{\scriptscriptstyle DQ}$ = 285 mA, Frequency = 7.9 GHz
OQPSK Linearity	ACLR4	Ŧ	-38.5	-32.5	dB	V_{DD} = 28 V, I_{DQ} = 285 mA, Frequency = 8.4 GHz

Notes:

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Test Methodology
Human Body Model	НВМ	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	II (200 < 500 V)	JEDEC JESD22 C101-C

¹ Measured in the CMPA5585025F-TB.

² Under OQPSK modulated signal, 1.6 Msps, PN23, Alpha Filter = 0.2.

 $^{^{3}}$ Measured at $P_{AVE} = 40$ dBm.

⁴ Fixture loss de-embedded.



Figure 1. CMPA5585025F Linear Output Power, Gain and PAE at -30 dBc, 1.6 MHz from carrier $V_{\rm DD} = 28 \text{ V}$, $I_{\rm DO} = 285 \text{ mA}$, 1.6 Msps OQPSK Modulation

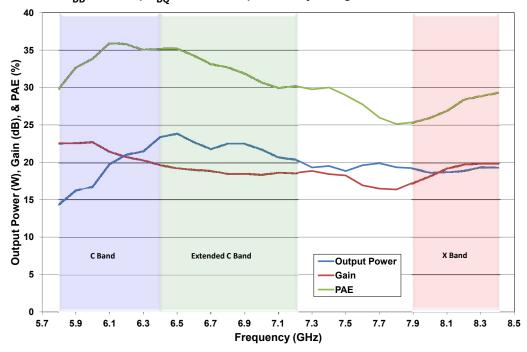


Figure 2. Typical Small Signal Gain and Return Loss vs Frequency of the CMPA5585025F measured in CMPA5585025F-TB Amplifier Circuit.

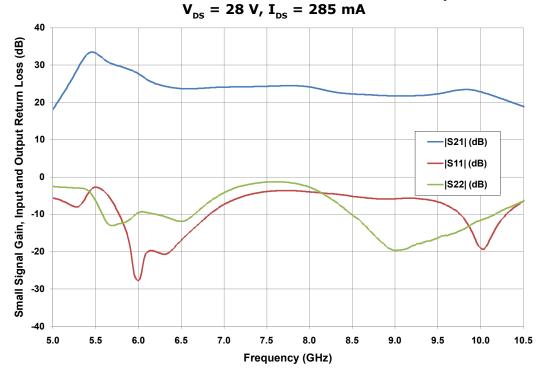




Figure 3. CMPA5585025F C-band Spectral Mask at 15 W PAE = 29.1% at 5.8 GHz, 28.5% at 6.4 GHz & 25.6% at 7.2 GHz

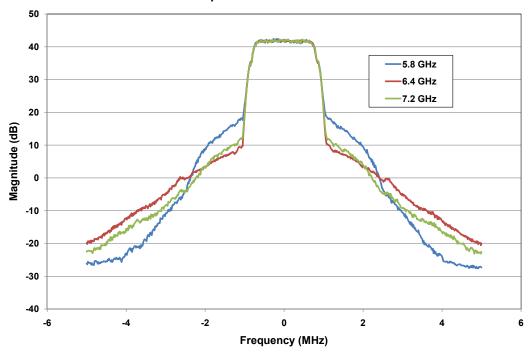


Figure 4. CMPA5585025F X-band Spectral Mask at 15 W PAE = 25.6% at 7.9 GHz & 25.3% at 8.4 GHz

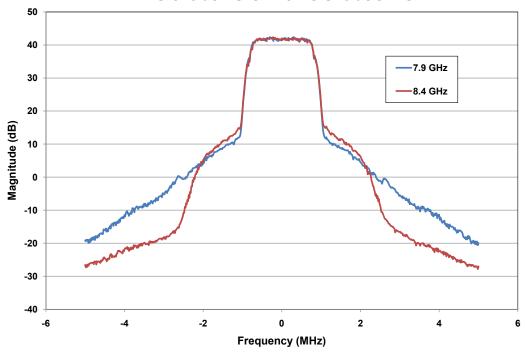




Figure 5. CMPA5585025F C-band Linearity, Gain, and PAE vs Average Output Power $V_{DS} = 28 \text{ V}, I_{DS} = 285 \text{ mA}, OQPSK, 1.6 \text{ Msps}$

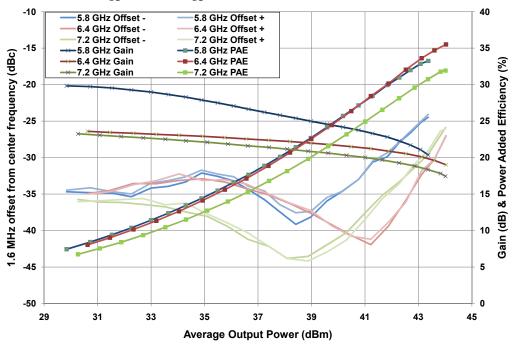


Figure 6. CMPA5585025F X-band Linearity, Gain, and PAE vs Average Output Power $V_{DS}=28~V,~I_{DS}=285~mA,~OQPSK,~1.6~Msps$

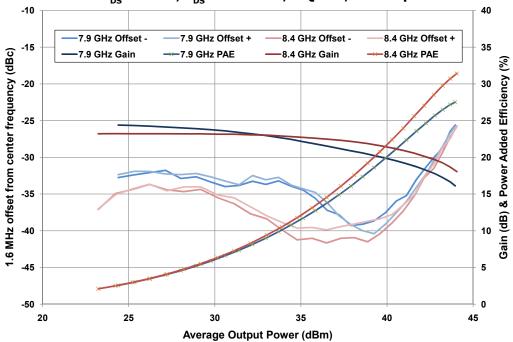




Figure 7. CMPA5585025F EVM vs Average Output Power $V_{DS} = 28 \text{ V}$, $I_{DS} = 285 \text{ mA}$, 1.6 Msps OQPSK Modulation

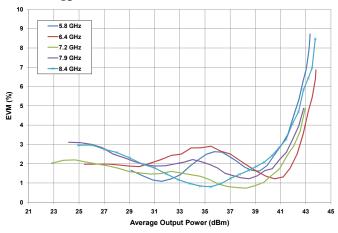


Figure 8. CMPA5585025F - Linearity vs Average Output Power OQPSK, 1.6 Msps, I_{DS} = 285 mA

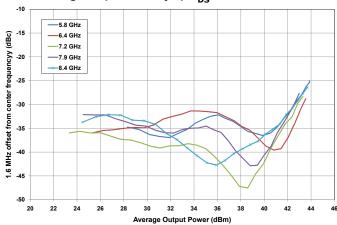
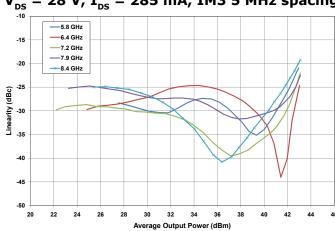


Figure 9. CMPA5585025F Linearity vs Average Output Power $V_{\rm DS}$ = 28 V, $I_{\rm DS}$ = 285 mA, IM3 5 MHz spacing



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Figure 10. CMPA5585025F - C-band Output Power, Gain and PAE vs Input Power $V_{\rm DS}$ = 28 V, $I_{\rm DS}$ = 1.2 A, CW

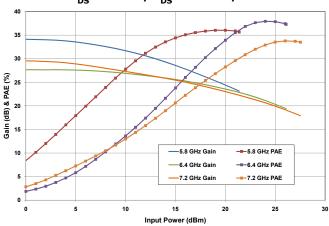


Figure 11. CMPA5585025F - X-band Output Power, Gain and PAE vs Input Power $V_{\rm DS}$ = 28 V, $I_{\rm DS}$ = 1.2 A, CW

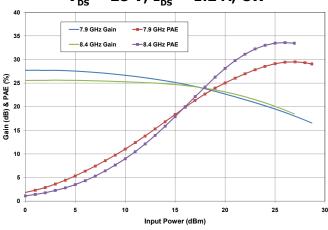
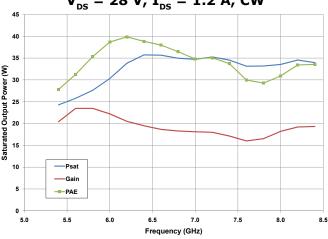


Figure 12. CMPA5585025F - Power, Gain and PAE vs Frequency $V_{\rm ps} = 28$ V, $I_{\rm ps} = 1.2$ A, CW



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Figure 13. CMPA5585025F - Typical Drain Current vs Average Output Power $V_{\rm DS}$ = 28 V, $I_{\rm DS}$ = 285 mA, OQPSK, 1.6 Msps

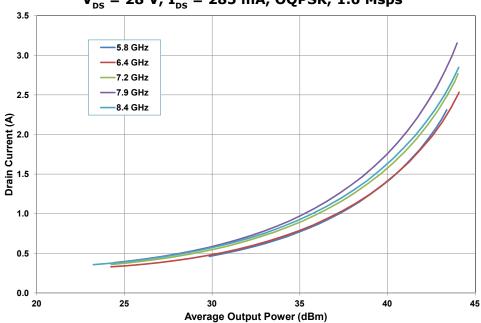
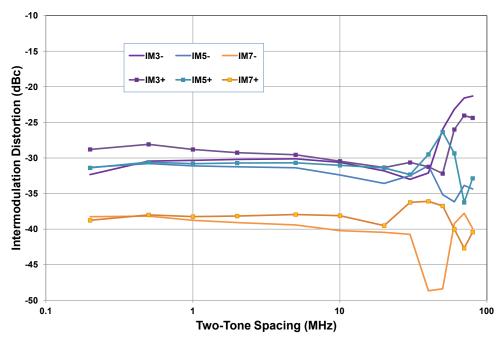


Figure 14. CMPA5585025F - Intermodulation Distortion Products vs Tone Spacing $V_{\rm DS}$ = 28 V, $I_{\rm DS}$ = 285 mA, Center Freq = 7.9 GHz



Note: Divergence in IM5 and IM7 at tone spacings greater than 20 MHz is due to the bias components on the test fixture.



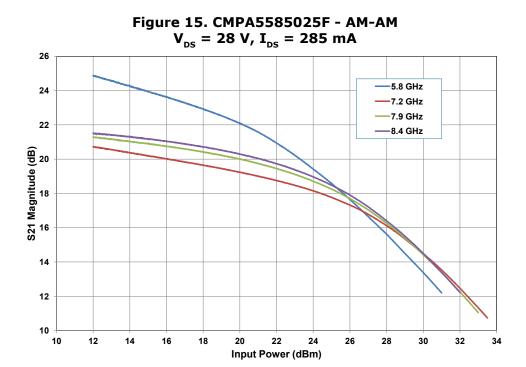
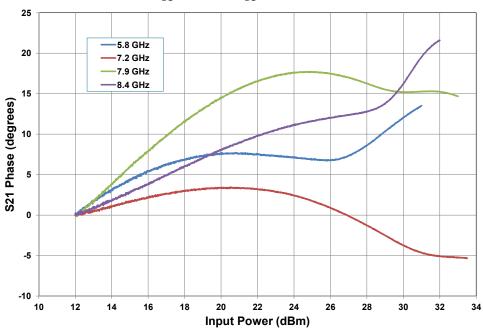


Figure 16. CMPA5585025F -Normalized AM-PM $V_{DS} = 28 \text{ V}, I_{DS} = 285 \text{ mA}$

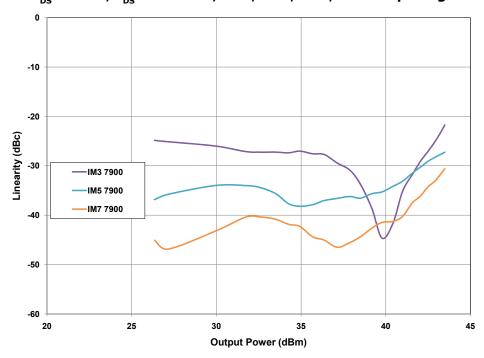




 $V_{DS} = 28 \text{ V, I}_{DS} = 285 \text{ mA, } 256 \text{ QAM}$ 5.0 4.5 4.0 3.5 3.0 2.5 2.0 1.5 6.4 EVM (%) 1.0 7.9 EVM (%) 8.4 EVM (%) 0.5 7.2 EVM (%) 0.0 20 45 Output Power (dBm)

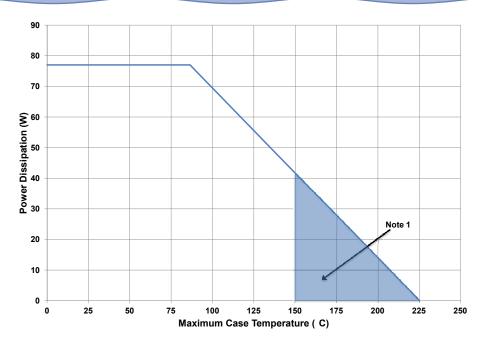
Figure 17. CMPA5585025F EVM vs Average Output Power

Figure 18. CMPA5585025F Linearity vs Average Output Power $V_{DS} = 28 \text{ V}, I_{DS} = 285 \text{ mA}, IM3, IM5, IM7, 5 MHz spacing}$





CMPA5585025F Power Dissipation De-rating Curve



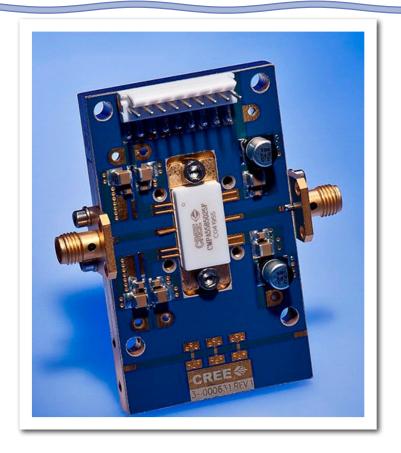
Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2).



CMPA5585025F-TB Demonstration Amplifier Circuit Bill of Materials

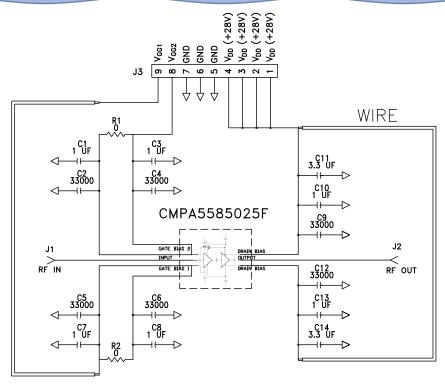
Designator	Description	Qty
C1, C3, C7, C8, C10, C13	CAP, 1.0 uF, +/-10%, 1210, 100V, X7R	6
C2, C4, C5, C6, C9, C12	CAP, 33000 pF, 0805, 100V, X7R	6
C11, C14	CAP ELECT 3.3UF 80V FK SMD	2
R1, R2	RES 0.0 OHM 1/16W 0402 SMD	2
J1,J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL	2
J3	CONNECTOR, HEADER, RT>PLZ .1CEN LK 9POS	1
-	PCB, TACONIC, RF-35P-0200-CL1/CL1	1
Q1	CMPA5585025F	1

CMPA5585025F-TB Demonstration Amplifier Circuit

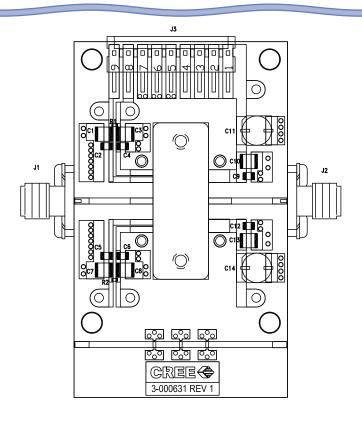




CMPA5585025F-TB Demonstration Amplifier Circuit



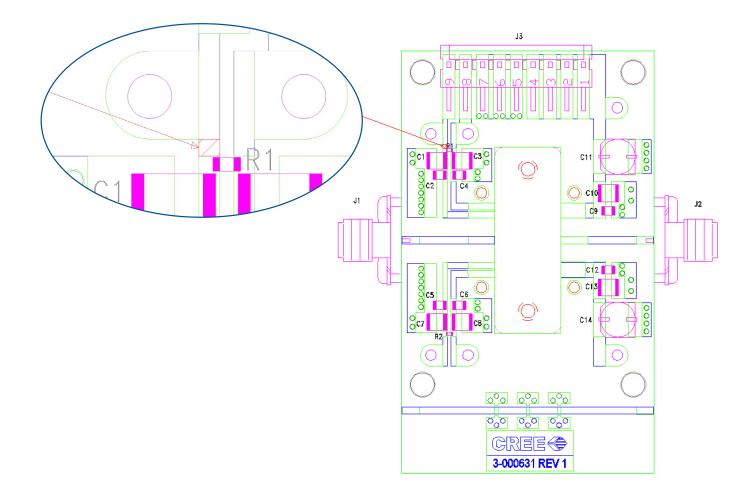
CMPA5585025F-TB Demonstration Amplifier Circuit Outline





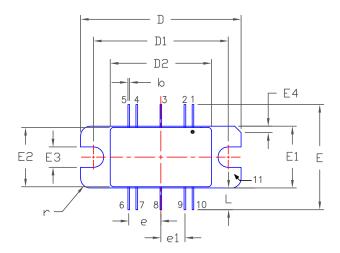
CMPA5585025F-TB Demonstration Amplifier Circuit

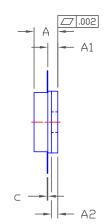
To configure the CMPA5585025F test fixture to enable independent $V_{\rm G1}$ / $V_{\rm G2}$ control of the device, a cut must be made to the microstrip line just above the R1 resistor as shown. Pin 9 will then supply $V_{\rm G1}$ and Pin 8 will supply $V_{\rm G2}$.





Product Dimensions CMPA5585025F (Package Type - 440208)





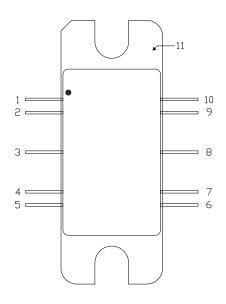
- PIN 1. GATE BIAS
 - 2. GATE BIAS
 - 3. RF INPUT
 - 4. GATE BIAS
 - 5. GATE BIAS
- 6. DRAIN BIAS
 - 7. DRAIN BIAS
 - 8. RF OUTPUT
 - DRAIN BIAS
 DRAIN BIAS
 - 11. SOURCE

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M $-\ 1994.$
- 2. CONTROLLING DIMENSION: INCH.
- 3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
- 4. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF 0.008' IN ANY DIRECTION.

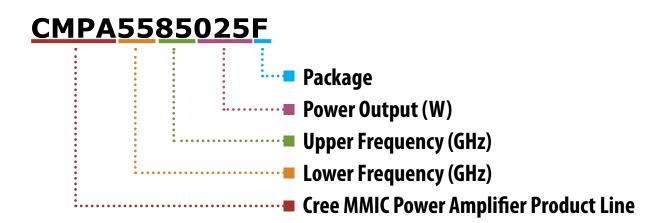
DI H PHATHON DI 0.000 IN HINI DINECTIDIN					
INCHES		MILLIM	NOTES		
MIN	MAX	MIN	MAX		
0.138	0.158	3.51	4.01		
0.057	0.067	1.45	1.70		
0.035	0.045	0.89	1.14		
0.01	TYP	0.254	TYP	10x	
0.003	0.006	0.08	0.15		
0.995	1.005	25.27	25.53		
0.835	0.845	21.21	21.46		
0.623	0.637	15.82	16.18		
0.654	TYP	16.61	TYP		
0.380	0.390	9.65	9.91		
0.365	0.375	9.72	9.53		
0.123	0.133	3.12	3.38		
0.035	0.045	0.89	1.14		
0.200 TYP		5.08 TYP		4x	
0.150 TYP		3.81	TYP	4x	
0.115	0.155	2.92	3.94	10x	
0.06	TYP	1.52	TYP	4x	
	INC MIN 0.138 0.057 0.035 0.001 0.003 0.995 0.835 0.623 0.654 0.380 0.365 0.123 0.035 0.123	INC+ES MIN MAX 0.138 0.158 0.057 0.067 0.035 0.045 0.003 0.006 0.995 1.005 0.835 0.845 0.623 0.637 0.654 TYP 0.380 0.390 0.365 0.375 0.123 0.133 0.035 0.045 0.200 TYP 0.115 TYP	INCHES MILLIM MIN MAX MIN 0.138 0.158 3.51 0.057 0.067 1.45 0.035 0.045 0.89 0.01 TYP 0.254 0.003 0.006 0.08 0.995 1.005 25.27 0.835 0.845 21.21 0.623 0.637 15.82 0.654 TYP 16.61 0.380 0.390 9.65 0.365 0.375 9.72 0.123 0.133 3.12 0.035 0.045 0.89 0.200 TYP 5.08 0.150 TYP 3.81 0.115 0.155 2.92	INCHES MILLIMETERS MIN MAX MIN MAX 0.138 0.158 3.51 4.01 0.057 0.067 1.45 1.70 0.035 0.045 0.89 1.14 0.01 TYP 0.254 TYP 0.003 0.006 0.08 0.15 0.995 1.005 25.27 25.53 0.835 0.845 21.21 21.46 0.623 0.637 15.82 16.18 0.654 TYP 16.61 TYP 0.380 0.390 9.65 9.91 0.365 0.375 9.72 9.53 0.123 0.133 3.12 3.38 0.035 0.045 0.89 1.14 0.200 TYP 5.08 TYP 0.150 TYP 3.81 TYP 0.115 0.155 2.92 3.94	

Pin Number	Qty
1	Gate Bias for Stage 2
2	Gate Bias for Stage 2
3	RF In
4	Gate Bias for Stage 1
5	Gate Bias for Stage 1
6	Drain Bias
7	Drain Bias
8	RF Out
9	Drain Bias
10	Drain Bias
11	Source





Part Number System



Parameter	Value	Units
Lower Frequency	5.5	GHz
Upper Frequency ¹	8.5	GHz
Power Output	25	W
Package	Flange	-

Table 1.

Note¹: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value
А	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

Table 2.



Disclaimer

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